

IDT71256SA

- 32K x 8 advanced high-speed CMOS static RAM
- Equal access and cycle times
 - Military: 15/20/25ns
 - Commercial: 12/15/20/25ns
- One Chip Select plus one Output Enable pin
- Bidirectional data inputs and outputs directly TTL-compatible
- Low power consumption via chip deselect
- Military product compliant to MIL-STD-883, Class B
- Available in 28-pin Sidebrake DIP, Plastic DIP, Plastic SOJ, and 32-pin LCC packages

The ID71256SA is a 262,144-bit high-speed Static RAM organized as 32K x 8. It is fabricated using IDT's high-performance, high-reliability CMOS technology. This state-of-the-art technology, combined with innovative circuit design techniques, provides a cost-effective solution for high-speed memory needs.

The IDT71256SA has an output enable pin which operates as fast as 6ns, with address access times as fast as 12ns. All bidirectional inputs and outputs of the IDT71256SA are TTL-compatible and operation is from a single 5V supply. Fully static asynchronous circuitry is used, requiring no clocks or refresh for operation.

The IDT71256SA is packaged in 28-pin 300 mil Sidebrazed DIP, 28-pin 300 mil Plastic DIP, 28-pin 300 mil Plastic SOJ, and 32-pin Leadless Chip Carrier packages.

The diagram illustrates the internal architecture of the 68000 microprocessor. On the left, a vertical stack of inputs labeled A₀ through A₁₄ feeds into an "ADDRESS DECODER". The output of the decoder is a set of 16 horizontal arrows pointing right into a large rectangular block labeled "262,144-BIT MEMORY ARRAY". Below the memory array, there are eight vertical double-headed arrows connecting it to a horizontal bar representing the bus. This bar connects to the top of a block labeled "I/O CONTROL". To the left of the I/O control block, the bus signal is shown as "I/O₀ - I/O₇" with an "8" indicating its width. Two inverters are connected to this bus: one inverts the signal before it enters the I/O control block, and the other inverts it before entering the "CONTROL LOGIC" block at the bottom. The CONTROL LOGIC block has three inputs on its left: CS (with a bubble), WE (with a bubble), and OE (with a bubble). It also receives two signals from the I/O control block via vertical lines. Finally, eight vertical arrows point down from the I/O control block to the bus.

2948 drw 01

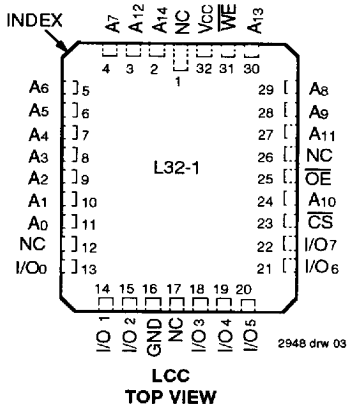
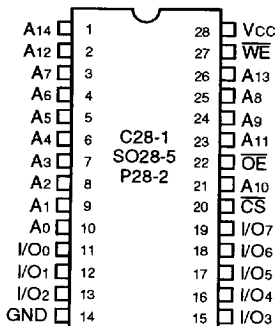
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PIN CONFIGURATIONS



RECOMMENDED DC OPERATING CONDITIONS

Symbol	Parameter	Min.	Typ.	Max.	Unit
V _{CC}	Supply Voltage	4.5	5.0	5.5	V
GND	Supply Voltage	0	0	0	V
V _{IH}	Input High Voltage	2.2	—	V _{CC} +0.5	V
V _{IL}	Input Low Voltage	-0.5 ⁽¹⁾	—	0.8	V

NOTE:
1. V_{IL} (min.) = -1.5V for pulse width less than 10ns, once per cycle.

DC ELECTRICAL CHARACTERISTICS

V_{CC} = 5.0V ± 10%

Symbol	Parameter	Test Condition	IDT71256SA		Unit
			Min.	Max.	
I _{LI}	Input Leakage Current	V _{CC} = Max., V _{IN} = GND to V _{CC}	—	5	μA
I _{LO}	Output Leakage Current	V _{CC} = Max., CS = V _{IH} , V _{OUT} = GND to V _{CC}	—	5	μA
V _{OL}	Output Low Voltage	I _{OL} = 8mA, V _{CC} = Min	—	0.4	V
V _{OH}	Output High Voltage	I _{OH} = -4mA, V _{CC} = Min	2.4	—	V

2948 tbl 05

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Rating	Com'l.	Mil.	Unit
V _{TERM} ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +7.0	-0.5 to +7.0	V
T _A	Operating Temperature	0 to +70	-55 to +125	°C
T _{BIAS}	Temperature Under Bias	-55 to +125	-65 to +135	°C
T _{STG}	Storage Temperature	-55 to +125	-65 to +150	°C
P _T	Power Dissipation	1.0	1.0	W
I _{OUT}	DC Output Current	50	50	mA

NOTES:

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1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

2. V_{TERM} must not exceed V_{CC} + 0.5V.

CAPACITANCE

(T_A = +25°C, f = 1.0MHz, SOJ package)

Symbol	Parameter ⁽¹⁾	Conditions	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 3dV	11	pF
C _{I/O}	I/O Capacitance	V _{OUT} = 3dV	11	pF

NOTE:

2948 tbl 03

1. This parameter is guaranteed by device characterization, but not production tested.

TRUTH TABLE^(1,2)

CS	OE	WE	I/O	Function
L	L	H	DATA _{OUT}	Read Data
L	X	L	DATA _{IN}	Write Data
L	H	H	High-Z	Outputs Disabled
H	X	X	High-Z	Deselected — Standby (I _{SB})
V _{HC} ⁽³⁾	X	X	High-Z	Deselected — Standby (I _{SB1})

NOTES:

2948 tbl 01

1. H = V_{IH}, L = V_{IL}, X = Don't care.

2. V_{LC} = 0.2V, V_{HC} = V_{CC} - 0.2V.

3. Other inputs ≥ V_{HC} or ≤ V_{LC}.

DC ELECTRICAL CHARACTERISTICS⁽¹⁾(V_{CC} = 5.0V ± 10%, V_{LC} = 0.2V, V_{HC} = V_{CC} - 0.2V)

Symbol	Parameter	71256SA12		71256SA15		71256SA20		71256SA25		Unit
		Com'l.	Mil.	Com'l.	Mil.	Com'l.	Mil.	Com'l.	Mil.	
I _{CC}	Dynamic Operating Current $\overline{CS} \leq V_{IL}$, Outputs Open, V _{CC} = Max, f = f _{MAX} ⁽²⁾	160	—	150	170	145	150	145	150	mA
I _{SB}	Standby Power Supply Current (TTL Level) $\overline{CS} \geq V_{IH}$, Outputs Open, V _{CC} = Max, f = f _{MAX} ⁽²⁾	50	—	40	50	40	45	40	45	mA
I _{SB1}	Standby Power Supply Current (CMOS Level) $\overline{CS} \geq V_{HC}$, Outputs Open, V _{CC} = Max, f = 0 ⁽²⁾ V _{IN} ≤ V _{LC} or V _{IN} ≥ V _{HC}	15	—	15	30	15	30	15	30	mA

NOTES:

- 1 All values are maximum guaranteed values
- 2 f_{MAX} = 1/t_{rc} (all address inputs are cycling at f_{MAX}), f = 0 means no address input lines are changing

2948 tbl 06

AC TEST CONDITIONS

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
AC Test Load	See Figures 1 and 2

2948 tbl 07

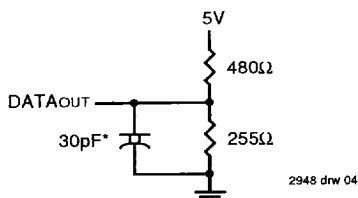
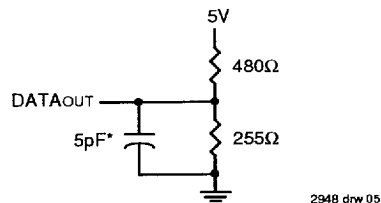


Figure 1. AC Test Load

Figure 2. AC Test Load
(for t_{CLZ}, t_{OLZ}, t_{CHZ}, t_{OHZ}, t_{OW}, and t_{WHZ})

*Including jig and scope capacitance.

AC ELECTRICAL CHARACTERISTICS ($V_{CC} = 5.0V \pm 10\%$, All Temperature Ranges)

Symbol	Parameter	71256SA12 ⁽¹⁾		71256SA15		71256SA20		71256SA25		
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Read Cycle										
tRC	Read Cycle Time	12	—	15	—	20	—	25	—	ns
tAA	Address Access Time	—	12	—	15	—	20	—	25	ns
tACS	Chip Select Access Time	—	12	—	15	—	20	—	25	ns
tCLZ ⁽²⁾	Chip Select to Output in Low-Z	4	—	4	—	4	—	4	—	ns
tCHZ ⁽²⁾	Chip Deselect to Output in High-Z	0	6	0	7	0	10	0	11	ns
tOE	Output Enable to Output Valid	—	6	—	7	—	10	—	11	ns
tOLZ ⁽²⁾	Output Enable to Output in Low-Z	0	—	0	—	0	—	0	—	ns
tOHZ ⁽²⁾	Output Disable to Output in High-Z	0	6	0	6	0	8	0	10	ns
tOH	Output Hold from Address Change	3	—	3	—	3	—	3	—	ns
tPU ⁽²⁾	Chip Select to Power Up Time	0	—	0	—	0	—	0	—	ns
tPD ⁽²⁾	Chip Deselect to Power Down Time	—	12	—	15	—	20	—	25	ns
Write Cycle										
tWC	Write Cycle Time	12	—	15	—	20	—	25	—	ns
tAW	Address Valid to End of Write	9	—	10	—	15	—	20	—	ns
tCW	Chip Select to End of Write	9	—	10	—	15	—	20	—	ns
tAS	Address Set-up Time	0	—	0	—	0	—	0	—	ns
tWP	Write Pulse Width	9	—	10	—	15	—	20	—	ns
tWR	Write Recovery Time	0	—	0	—	0	—	0	—	ns
tDW	Data Valid to End of Write	6	—	7	—	11	—	13	—	ns
tDH	Data Hold Time	0	—	0	—	0	—	0	—	ns
tOW ⁽²⁾	Output Active from End of Write	4	—	4	—	4	—	4	—	ns
tWHZ ⁽²⁾	Write Enable to Output in High-Z	0	6	0	6	0	10	0	11	ns

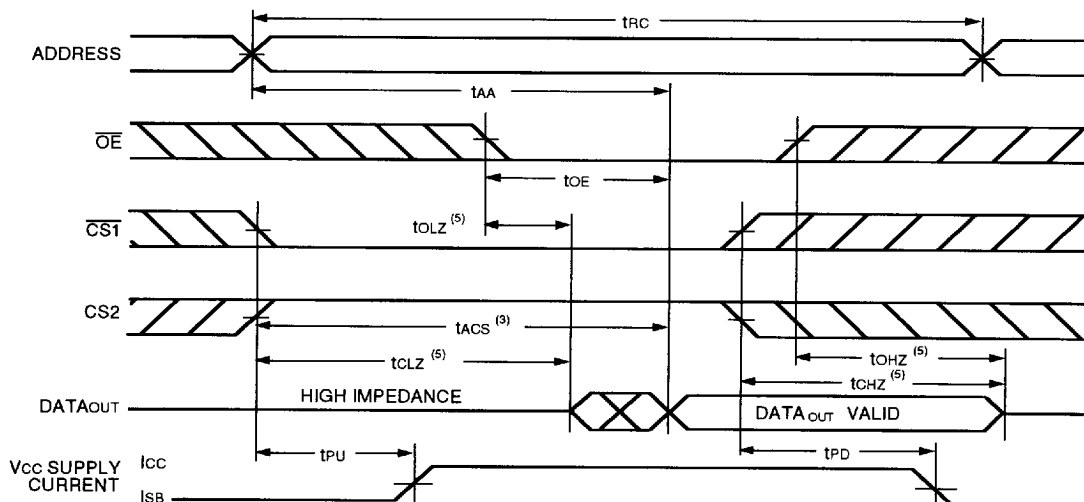
NOTES:

1. 0° to +70°C temperature range only

2. This parameter is guaranteed with the AC Load (Figure 2) by device characterization, but is not production tested

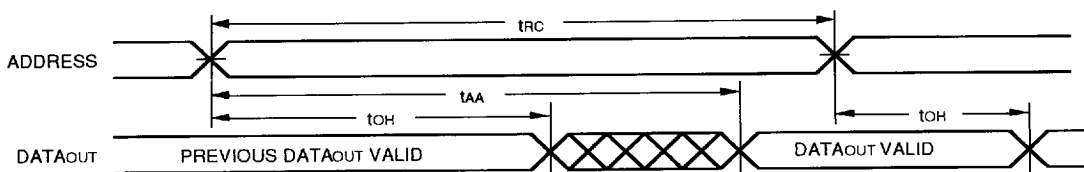
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TIMING WAVEFORM OF READ CYCLE NO. 1⁽¹⁾

2948 dw 06

TIMING WAVEFORM OF READ CYCLE NO. 2^(1,2,4)

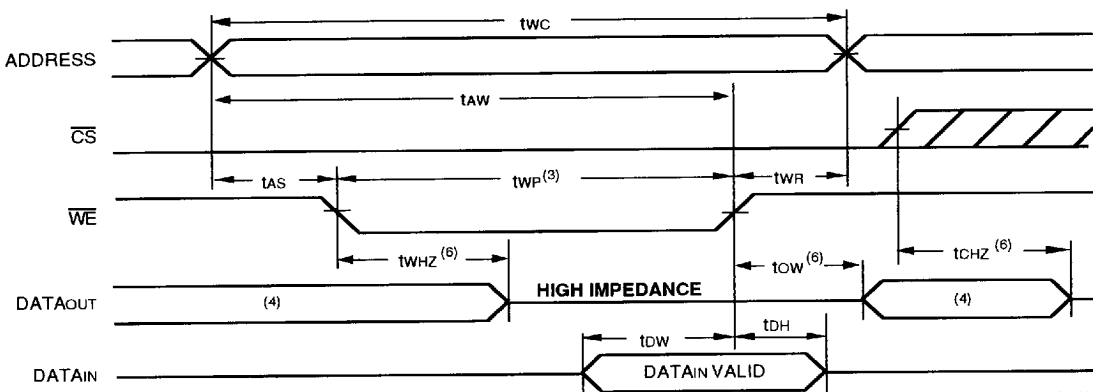


NOTES:

1. WE is HIGH for Read Cycle
2. Device is continuously selected, $\overline{CS}$ is LOW
3. Address must be valid prior to or coincident with the later of $\overline{CS}$ transition LOW, otherwise t_{AA} is the limiting parameter
4. $\overline{OE}$ is LOW
5. Transition is measured $\pm 200\text{mV}$ from steady state.

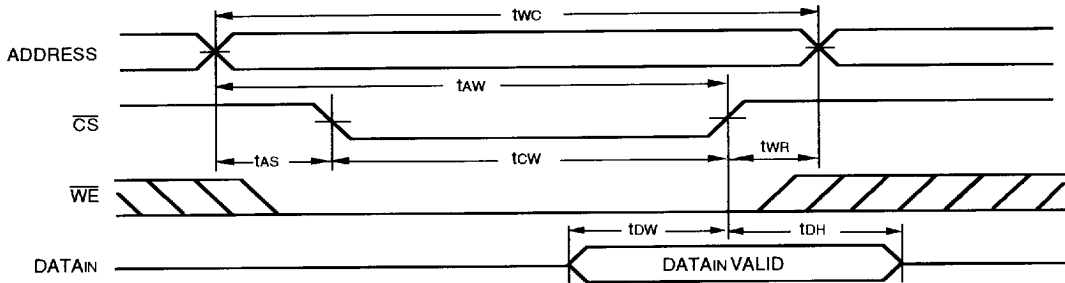
2948 drw 07

TIMING WAVEFORM OF WRITE CYCLE NO.1 ($\overline{WE}$ CONTROLLED TIMING)^(1,2,3,5)



2948 drw 08

TIMING WAVEFORM OF WRITE CYCLE NO.2 ($\overline{CS}$ CONTROLLED TIMING)^(1,2,5)

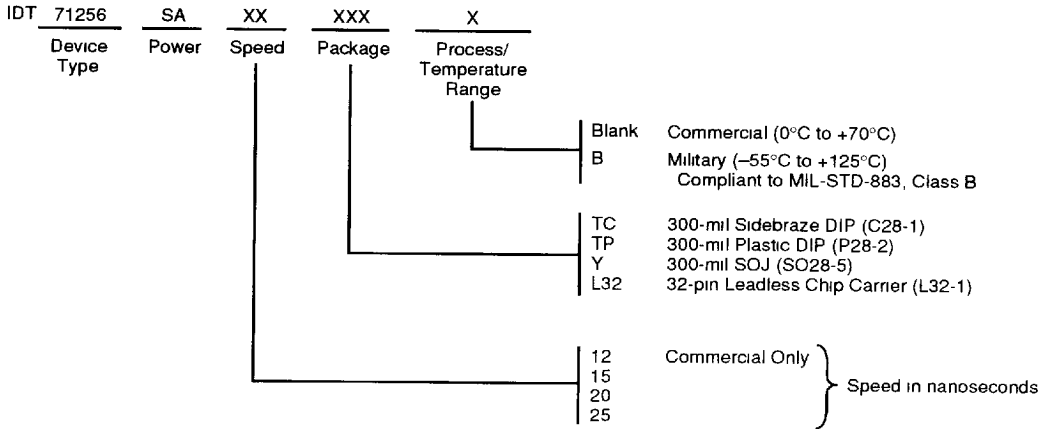


2948 drw 09

NOTES:

1. WE or $\overline{CS}$ must be HIGH during all address transitions
2. A write occurs during the overlap of a LOW $\overline{CS}$ and a LOW $\overline{WE}$
3. $\overline{OE}$ is continuously HIGH. If during a WE controlled write cycle $\overline{OE}$ is LOW, t_{WP} must be greater than or equal to $t_{WHZ} + t_{DW}$ to allow the I/O drivers to turn off and data to be placed on the bus for the required t_{DW} . If $\overline{OE}$ is HIGH during a WE controlled write cycle, this requirement does not apply and the minimum write pulse is as short as the specified t_{WP}
4. During this period, I/O pins are in the output state, and input signals must not be applied.
5. If the $\overline{CS}$ LOW transition occurs simultaneously with or after the $\overline{WE}$ LOW transition, the outputs remain in a high-impedance state.
6. Transition is measured $\pm 200\text{mV}$ from steady state

ORDERING INFORMATION



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